

SCIENCE ENGINEER

🔄 13 марта 2023 📍 Город: [Киев](#)

📍 Готов к командировкам: [Львов](#), [Черновцы](#), [Ивано-Франковск](#)

Возраст: 37 лет

Режим работы: полный рабочий день, свободный график работы, посменная работа

Категории: IT, WEB специалисты, Наука, образование, переводы, Производство

✓ Готов к командировкам

Опыт работы

Experimental setup operator role

Taras Shevchenko National University of Kyiv (Science), Киев

05.2018 – 08.2021 (3 года 3 месяца)

Обязанности:

Experiment design role at laboratory of Institute of high technologies at the department of Nano physics condensed matter.

Adjusting, hardware and software implementing, service providing of experimental setup.

and providing.

Precision hand work up to 50 mkm resolution of positioning in combine with software programming such as Labview for instance. Measurements of samples at wide temperature range.

Performance at thematic scientific conferences.

Several articles at stock.

✓ Есть рекомендации с данного места работы

Head of engineering team

Service of Apple devices (Electronic devices repairing company), Киев

12.2012 – 08.2020 (7 лет 8 месяцев)

Обязанности:

Troubleshooting and repair damaged motherboards of MacBooks, iPads, iPods and iPhones.

Soldering of 01005/008004 SMD components and BGA chips mont technology at various cases, such as under upgrade, modification or repair procedures.

Executive cellular phones Vertu repairing and servicing.

Experimental and custom projects team lead.

Prototyping and producing of miniaturized custom electronics.

Employing and training new stuff.

Образование

Taras Shevchenko National University of Kyiv (Киев)

Специальность: Radio physics Faculty, Department of Electro physics, specialization applied optics and magnetism

полное высшее, 09.2006 – 05.2012 (5 лет 7 месяцев)

Дополнительная информация

Личные качества, хобби, увлечения, навыки: Fast learning curve and strong adaptability. Scrupulous with attention to details. Strong interest to miniaturized electronic schematics at limited space of packaging and installing.